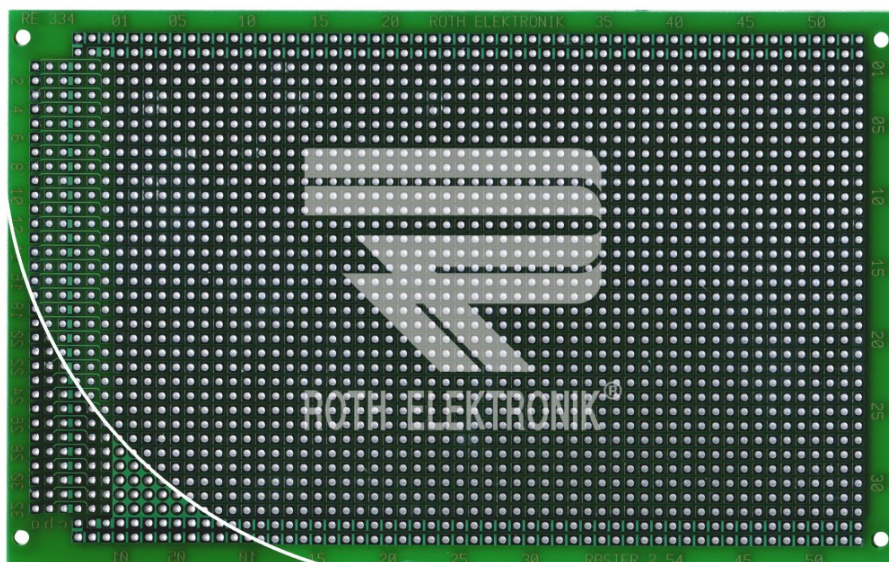


HF-board



RE334-LF



- EPOXY fibre-glass FR4 1.5 mm double-sided 35 µm CU (pth)
- hot air leveling (HAL-leadfree)
- 32 x 53 single-hole conductor 2.0 mm²
- hole spacing 2.54 x 2.54 mm
- hole dia 1.0 mm
- connector 32/64/96-channel
- DIN 41612 type C
- the component side is totally laminated by CU
- the through-holes are etched free so that a conducting connection to the other component side is impossible
- if the CU-coating is connected to ground the electrical components are optimally shielded against the solder side
- by this HF, digital and analog circuits can be built up with high reliability
- the component and solder side are laminated with solder lacquer and additional print
- size 100 x 160 mm